

## Gaskleen® II EL Purifier Assembly

### Description

Pall Gaskleen II EL purifier assemblies are designed to remove molecular contamination from many process gases. Sub-parts-per-billion (ppb) level purification is achieved for flow rates up to 30 slpm, with excursions up to 50 slpm<sup>1</sup>, while providing  $\geq 3$  nanometer (nm) particle removal.

- Controls and removes impurities such as moisture, oxygen, carbon dioxide, non-methane hydrocarbons, metal carbonyls, and siloxanes
- 316L stainless steel housing
- Wide variety of gases purified
- 100% helium leak and pressure tested
- Not orientation sensitive
- No detectable metal contribution above background in HCl gas with HCLP material
- No detectable metal contribution above background in HBr gas with HBRP material



### Specifications

<b>Materials</b>	<ul style="list-style-type: none"> <li>• Housing: electropolished 316L SS</li> <li>• <math>\leq 0.25 \mu\text{m} / 10 \text{ uin Ra}</math> internal surface finish</li> <li>• Housing meets or exceeds VIM / VAR specifications</li> </ul>
<b>Particle Removal Efficiency Rating</b>	<ul style="list-style-type: none"> <li>• <math>10^9</math> reduction for particles <math>\geq 3 \text{ nm}</math> up to 50 slpm<sup>3</sup></li> </ul>
<b>Connections</b>	<ul style="list-style-type: none"> <li>• <math>1/4</math>" Gasket Seal, Male / Male (VCR<sup>3</sup> or compatible)</li> </ul>

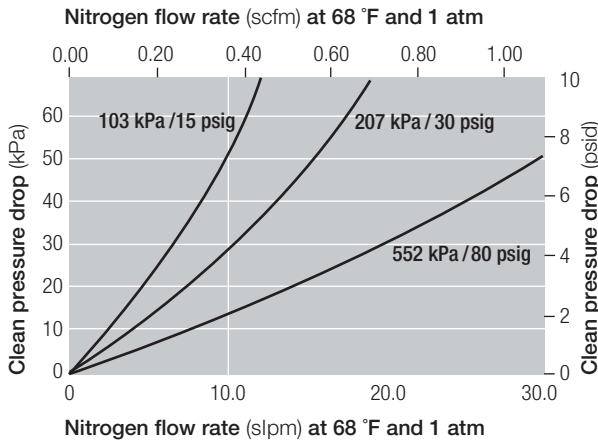
<b>Operating Conditions</b>	<ul style="list-style-type: none"> <li>• Maximum operating pressure: 6.9 MPa @ 100°C / 1,000 psig @ 212°F</li> <li>• Maximum operating temperature: 100°C / 212°F (INP, SIP, FCP, SF6P) 40°C / 104°F (GEH4P, OXP, CLXP, HCLP, HBRP, CDAP)</li> <li>• EU Pressure Equipment Directive: Assemblies comply with the European Union's Pressure Equipment Directive 2014/68/EC and are CE marked</li> </ul>
<b>Packaging</b>	<ul style="list-style-type: none"> <li>• Double bagged</li> <li>• Aluminized outer bag, polyethylene inner bag</li> <li>• End fittings sealed with metal gaskets and caps</li> <li>• Product sealed in an argon environment</li> </ul>

<sup>1</sup> Contact the Pall Microelectronics group for further information.

<sup>2</sup> Particle rating based on laboratory testing with NaCl aerosol.

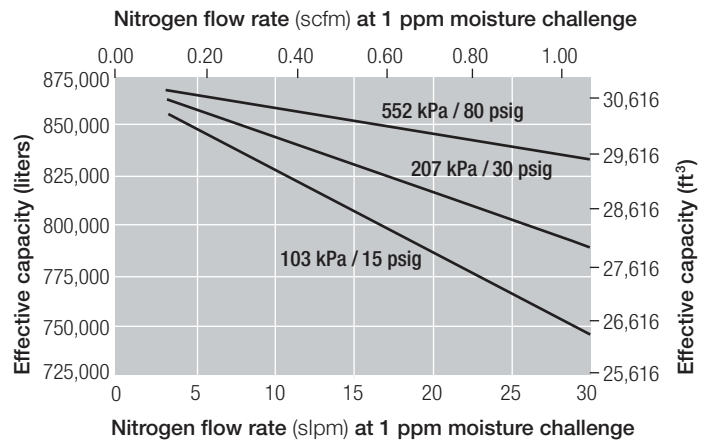
<sup>3</sup> VCR is a trademark of Swagelok Co.

## Pressure Drop vs. Flow Rate



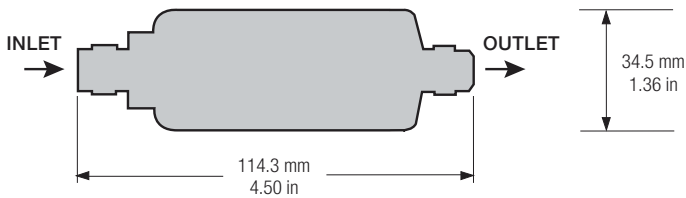
Unit conversion: 1 bar = 100 kilopascals

## Effective Capacity<sup>5</sup>



<sup>5</sup> For application specific calculations, please contact Pall Microelectronics.

## Dimensions



## Part Numbers / Ordering Information

Part Number Specifications	Specific Gas	Effluent Impurity Specifications
GLP6INPVMM4	Inert Gases: Nitrogen, Argon, Helium, Xenon, Krypton, Neon	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , CO
GLP6SIPVMM4	Flammable Gases: Silane, Hydrogen, Methane, Ethane, Cyclopropane, Propane, Dimethyl Ether, Ethylene, Propylene, Carbonyl Sulfide Carbon Monoxide	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , CO < 1 ppb H <sub>2</sub> O, O <sub>2</sub> , CO <sub>2</sub> , Fe(CO) <sub>5</sub> < 10 ppb Ni(CO) <sub>4</sub>
GLP6FCPVMM4	Fluoromethane, Difluoromethane, Trifluoromethane, Tetrafluoroethane, Pentafluoroethane, Heptafluoropropane, Carbon Tetrafluoride, Perfluoropropane, Perfluorocyclobutane, Hexafluoroethane	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub>
GLP6GEH4PVMM4	Germane	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , CO
GLP6SF6PVMM4	Sulfur Hexafluoride	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , CO
GLP6OXPVMM4	Oxygenated Gases: Carbon Dioxide, Oxygen, Nitrous Oxide	< 10 ppb H <sub>2</sub> O
GLP6CLXPVMM4	Chlorinated Gases: Boron Trichloride, Chlorine, Trichlorosilane, Dichlorosilane	< 100 ppb H <sub>2</sub> O
GLP6HCLPVMM4	Hydrogen Chloride	< 15 ppb H <sub>2</sub> O
GLP6HBRPVMM4	Hydrogen Bromide	< 50 ppb H <sub>2</sub> O
GLP6CDAPVMM4	Photolithography clean dry air	< 1 ppb H <sub>2</sub> O, < 300 ppt organics (as C <sub>4</sub> ), < 10 ppt acid gases (as SO <sub>2</sub> ), < 15 ppt basic gases (as NH <sub>3</sub> ), < 1 ppt refractory compounds (as HMDSO)

## Technical Information

### Impurity Removal as Tested in Specific Gases

Specific Gas	Impurity Removal Efficiency
Inert Gases: Nitrogen, Argon, Helium, Xenon, Krypton, Neon	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , and CO as tested in argon and nitrogen
Flammable Gases: Silane, Hydrogen, Methane, Ethane, Cyclopropane, Propane, Dimethyl Ether, Ethylene, Propylene, Carbonyl Sulfide	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , and CO as tested in argon, < 1 ppb H <sub>2</sub> O as tested in carbon monoxide using trace moisture analyzer H <sub>2</sub> O and siloxanes removed to trace levels as tested in silane using APIMS
Carbon Monoxide	< 10 ppb Ni(CO) <sub>4</sub> and < 1 ppb Fe(CO) <sub>5</sub> as tested in carbon monoxide using GC-ECD analyzer
Fluoromethane, Difluoromethane, Trifluoromethane, Tetrafluoroethane, Pentafluoroethane, Heptafluoropropane, Carbon Tetrafluoride, Perfluoropropane, Perfluorocyclobutane, Hexafluoroethane	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , and CO as tested in argon and nitrogen using APIMS analyzer < 1 ppb O <sub>2</sub> as tested in trifluoromethane using trace oxygen analyzer < 10 ppb H <sub>2</sub> O as tested in trifluoromethane using trace moisture analyzer and FTIR
Germane	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , and O <sub>2</sub> as tested in argon using APIMS
Sulfur Hexafluoride	< 1 ppb H <sub>2</sub> O, CO <sub>2</sub> , O <sub>2</sub> , and CO as tested in argon and nitrogen
Oxygenated Gases: Carbon Dioxide, Oxygen, Nitrous Oxide	< 1 ppb H <sub>2</sub> O and CO <sub>2</sub> as tested in argon using APIMS analyzer
Chlorinated Gases: Boron Trichloride, Chlorine, Trichlorosilane, Dichlorosilane	< 1 ppb H <sub>2</sub> O and CO <sub>2</sub> as tested in argon using APIMS analyzer
Hydrogen Chloride	< 15 ppb H <sub>2</sub> O as tested in hydrogen chloride using CRDS < 1 ppb H <sub>2</sub> O as tested in argon using APIMS analyzer
Hydrogen Bromide	< 50 ppb H <sub>2</sub> O as tested in hydrogen bromide using CRDS < 1 ppb H <sub>2</sub> O as tested in argon using APIMS analyzer
Photolithography Clean Dry Air	< 1 ppb H <sub>2</sub> O as tested in argon using APIMS analyzer < 300 ppt C <sub>4</sub> H <sub>8</sub> as tested in argon using APIMS analyzer < 10 ppt SO <sub>2</sub> as tested in nitrogen using ion chromatograph < 15 ppt NH <sub>3</sub> as tested in nitrogen using ion chromatograph < 1 ppt HMDSO as tested in argon using APIMS analyzer and baseline subtraction



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